

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

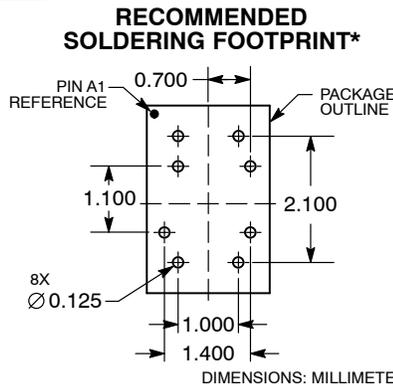
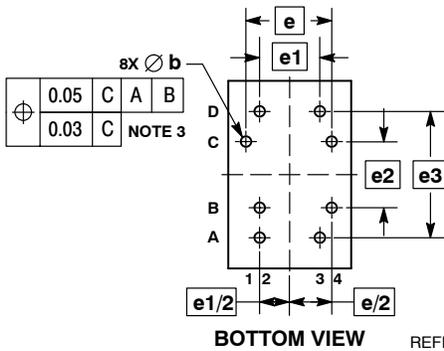
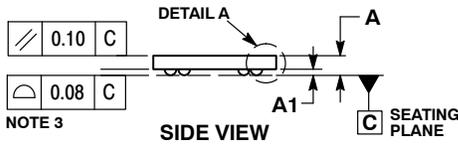
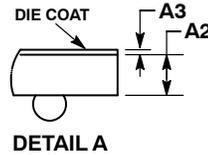
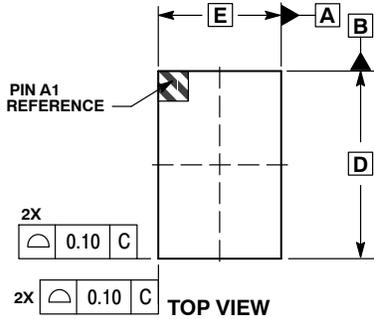
ON Semiconductor®



SCALE 4:1

WLCSP8, 3.12x2.04
CASE 567GV
ISSUE B

DATE 17 FEB 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.37
A1	0.06	0.10
A2	0.23	REF
A3	0.025	REF
b	0.11	0.14
D	3.12	BSC
E	2.04	BSC
e	1.40	BSC
e1	1.00	BSC
e2	1.10	BSC
e3	2.10	BSC

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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